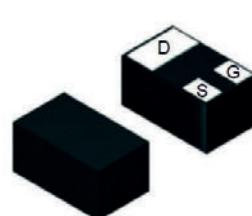
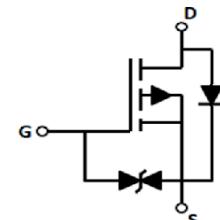


Main Product Characteristics

BV _{DSS}	-20V
R _{DS(ON)}	640mΩ (max.)
I _D	-0.66A



SOT-883



Schematic Diagram

Features and Benefits

- Advanced MOSFET process technology
- Ideal for high efficiency switched mode power supplies
- Low on-resistance with low gate charge
- Fast switching and reverse body recovery



Description

The GSFW02066 utilizes the latest techniques to achieve high cell density and low on-resistance. These features make this device extremely efficient and reliable for use in high efficiency switch mode power supplies and a wide variety of other applications.

Absolute Maximum Ratings (T_A=25°C unless otherwise specified)

Parameter	Symbol	Value	Unit
Drain-Source Voltage	V _{DS}	-20	V
Gate-Source Voltage	V _{GS}	±8	V
Drain Current-Continuous ¹	I _D	-0.66	A
Pulsed Drain Current	I _{DM}	-2.1	A
Power Dissipation ¹	P _D	0.15	W
Thermal Resistance from Junction to Ambient ¹	R _{θJA}	833	°C/W
Junction Temperature	T _J	150	°C
Storage Temperature	T _{stg}	-55 to +150	°C

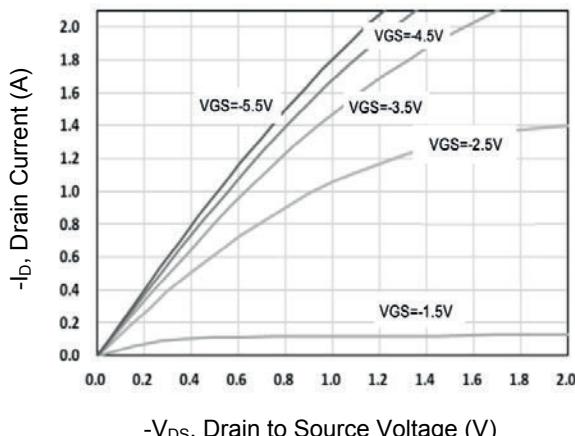

GSFW02066
20V P-Channel MOSFET
Electrical Characteristics (@ 25°C unless otherwise specified)

Parameter	Symbol	Test Conditions	Min	Typ	Max	Units
On / Off Characteristics						
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS}=0V, I_D=-250\mu A$	-20	-	-	V
Gate-Threshold Voltage ²	$V_{GS(th)}$	$V_{DS}=V_{GS}, I_D=-250\mu A$	-0.35	-0.45	-1.1	V
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS}=-20V, V_{GS}=0V$	-	-	-1.0	μA
Gate-Body Leakage Current	I_{GSS}	$V_{GS}=\pm 8V, V_{DS}=0V$	-	-	± 10	μA
Drain-Source On-Resistance ²	$R_{DS(on)}$	$V_{GS}=-4.5V, I_D=-0.55A$	-	530	640	$m\Omega$
		$V_{GS}=-2.5V, I_D=-0.45A$	-	730	950	$m\Omega$
		$V_{GS}=-1.8V, I_D=-0.35A$	-	1300	1950	$m\Omega$
Forward Transconductance	g_{fs}	$V_{DS}=-10V, I_D=-0.54A$	-	1.2	-	S
Dynamic and Switching Characteristics						
Input Capacitance ⁴	C_{iss}	$V_{DS}=-10V, V_{GS}=0V, F=1MHz$	-	58	-	pF
Output Capacitance ⁴	C_{oss}		-	5.7	-	
Reverse Transfer Capacitance ⁴	C_{rss}		-	4.4	-	
Turn-on Delay Time ^{3,4}	$t_{d(on)}$	$V_{GS}=-10V, V_{DD}=-4.5V, I_D=-1.33A, R_{GEN}=3\Omega$	-	0.4	-	nS
Turn-on Rise Time ^{3,4}	t_r		-	0.06	-	
Turn-off Delay Time ^{3,4}	$t_{d(off)}$		-	0.02	-	
Turn-off Fall Time ^{3,4}	t_f		-	0.8	-	
Source-Drain Ratings and Characteristics						
Diode Forward Voltage	V_{SD}	$I_S=-0.5A, V_{GS}=0V$	-	-	-1.2	V

Note:

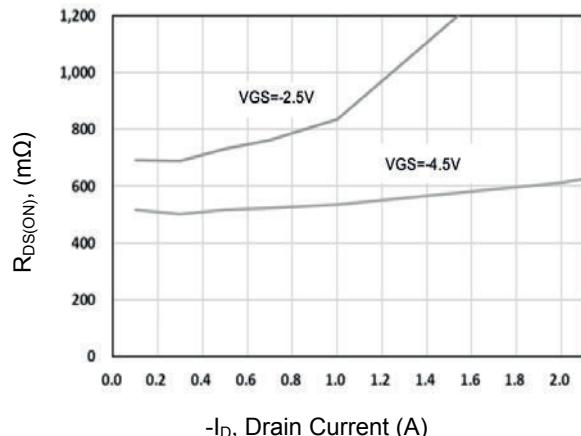
1. Surface mounted on FR4 board using the minimum recommended pad size.
2. Pulse test: pulse width=300 μs , duty cycle=2%.
3. Switching characteristics are independent of operating junction temperatures.
4. Guaranteed by design, not subject to producting.

Typical Performance Characteristics



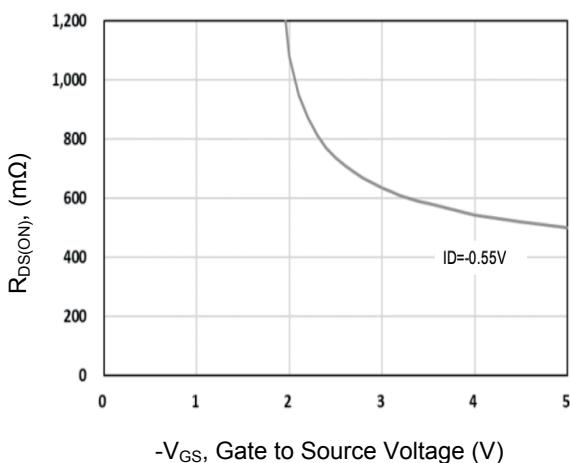
- V_{DS} , Drain to Source Voltage (V)

Figure 1. Output Characteristics



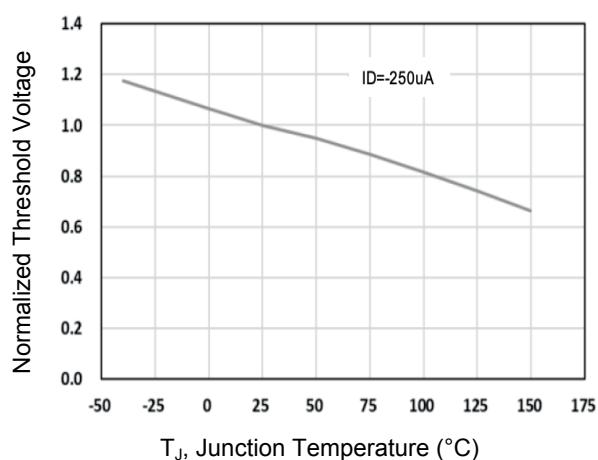
- I_D , Drain Current (A)

Figure 2. On-Resistance vs. Drain Current



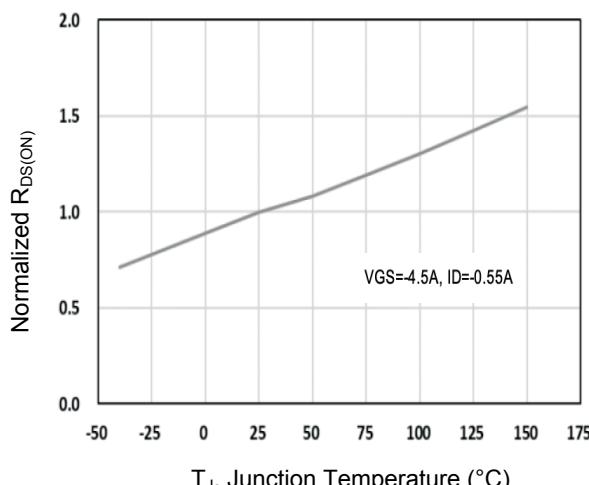
- V_{GS} , Gate to Source Voltage (V)

Figure 3. On-Resistance vs. Gate-Source Voltage



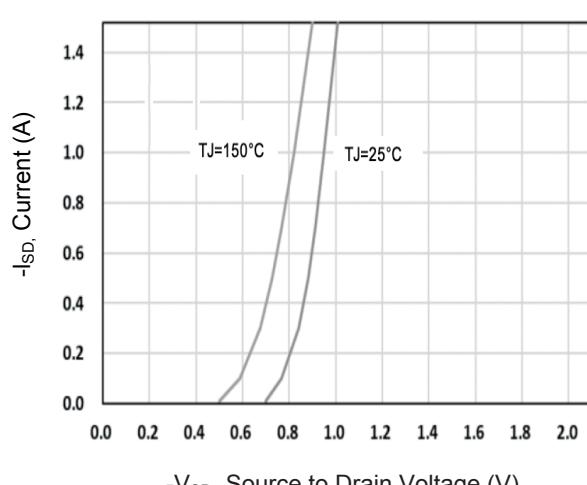
T_J , Junction Temperature (°C)

Figure 4. Gate Threshold Voltage



T_J , Junction Temperature (°C)

Figure 5. Drain to Source on Resistance



- V_{SD} , Source to Drain Voltage (V)

Figure 6. Source to Drain Diode Forward Voltage

Typical Performance Characteristics

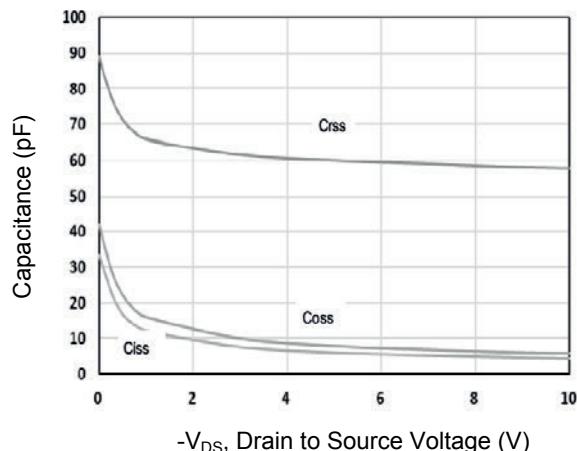


Figure 7. Capacitance

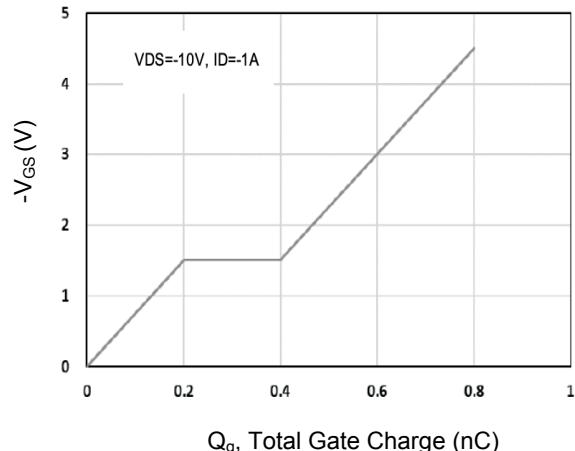
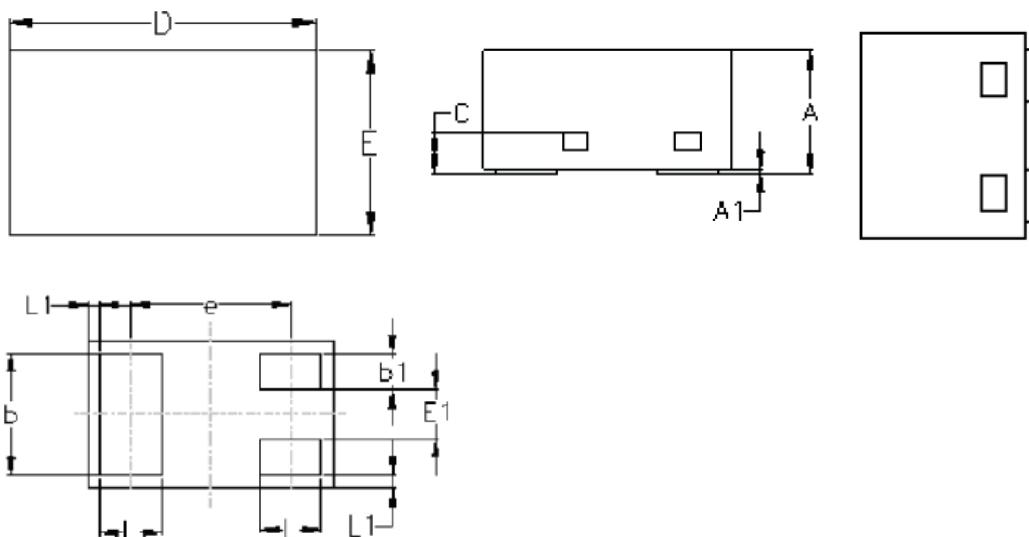


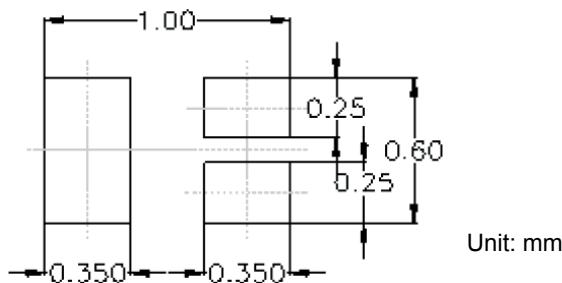
Figure 8. Gate Charge Characteristics

Package Outline Dimensions (SOT-883)



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	0.45	0.55	0.018	0.022
A1	0.00	0.05	0.000	0.002
b	0.45	0.55	0.018	0.022
b1	0.10	0.20	0.004	0.008
C	0.12	0.18	0.005	0.007
D	0.95	1.05	0.037	0.041
E	0.55	0.65	0.022	0.026
E1	0.15	0.25	0.006	0.010
e	0.65 BSC		0.026 BSC	
L	0.20	0.30	0.008	0.012
L1	0.05 REF		0.002 REF	

Recommended Pad Layout



Order Information

Device	Package	Marking	Carrier	Quantity
GSFW02066	SOT-883	39	Tape & Reel	10,000 pcs / 7" Reel